ABSTRACT

The present invention provides an electronic device manufacturing method and an electronic device which make it possible to reduce the waste of materials and the number of manufacturing steps required. Electronic devices are manufactured via a process including creating a collective substrate, in which a plurality of substrates corresponding to the electronic devices being manufactured are connected in the form of a matrix, mounting electronic parts on the upper surface of the collective substrate, forming a solidified resin layer using a vacuum printing method so that said resin layer covers the upper surface of the collective substrate on which the aforementioned parts have been mounted, or an intermediate layer consisting of an insulating elastic material, and so that said resin layer covers the electronic parts, and separating the collective substrate on which the above-mentioned resin layer has been formed into individual substrates. Since a collective substrate is used and electronic devices are obtained by ultimately separating this collective substrate, the waste of substrate material can be greatly reduced, and the number of manufacturing steps required can also be reduced.